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1 Article

Single Photon Counting Performance and Noise Analysis of CMOS SPAD-based Image Sensors

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Abstract: SPAD-based solid state CMOS image sensors utilising analogue integrators have attained deep sub electron read noise (DSERN) permitting single photon counting (SPC) imaging. A new method is proposed to determine the read noise in DSERN image sensors by evaluating the peak separation and width (PSW) of single photon peaks in a photon counting histogram (PCH). The technique is used to identify and analyse cumulative noise in analogue integrating SPC SPAD-based pixels. The DSERN of our SPAD image sensor is exploited to confirm recent multi-photon threshold quanta image sensor (QIS) theory. Finally, various single and multiple photon spatio-temporal

- 18 oversampling techniques are reviewed.
- Keywords: Single Photon Avalanche Diode, SPAD, CMOS Image Sensor, CIS, Single Photon
 Counting, SPC, Quanta Image Sensor, QIS, Spatio-Temporal Oversampling.
- 21

22 **1. Introduction**

23 Imaging a few photons per pixel, per frame, demands pixels operating in the single photon 24 counting regime. This challenge is encountered in either low-light or high-speed imaging; at long 25 integration times (ms to s) and low photon flux, or short integration times (µs or less) and high photon 26 flux, respectively. Examples are high-speed cameras for engine and exhaust combustion analysis, 27 low-light or night-vision cameras for defence [1], staring applications in astronomy and many 28 scientific applications such as, spectroscopy, fluorescence lifetime imaging microscopy (FLIM) [2][3], 29 positron emission tomography (PET) [4], fluorescence correlation spectroscopy (FCS) [5], Forster 30 Resonance Emission Tomography (FRET) [6], and in automotive applications for LIDAR [7].

31 For true photoelectron (or photon) counting to be reached, the ratio of the input sensitivity or 32 signal to the noise of the imaging system must be sufficiently high to allow discrete and resolvable 33 signal levels for each photoelectron to be discriminated. Referring the readout noise to the input 34 sensitivity in photoelectrons, the single photon counting regime is theoretically entered below 0.5e-35 input referred read noise (RN)[8], but practically there is a 90% accuracy of determining the number 36 of photoelectrons at 0.3e- RN, and approaching 100% accuracy at 0.15e- RN [9]. These probability 37 figures, assume RN is Gaussian distributed and the discrimination thresholds between one 38 photoelectron signal, to the next, are set precisely mid-way and do not take into account fixed pattern 39 noise (FPN) or gain variations in photo-response non-uniformity (PRNU). Such sensors in this 40 photon-counting regime with approximately <0.3e- RN may be referred to as deep sub-electron read 41 noise (DSERN) image sensors [10].

With high charge to voltage factor (CVF) sensitivity (or conversion gain (CG)), DSERN pixelshave limited photoelectron or photon counting capability (full well capacity), and therefore restricted

dynamic range (DR). DR may be extended by a range of techniques: exposure control with the capture
of multiple sequential images [11], pixel design with dual integrations (e.g. lateral overflow
integration capacitors (LOFIC) [12]), or by combining multiple pixel samples through spatiotemporal oversampling [13], [14]. In the latter the number of oversampled frames is traded off against
the frame rate.

This paper evaluates the single photon counting and noise characteristics of our recent work on SPAD-based image sensors [15]–[17] and analyses the benefits, tradeoffs and noise performance of various spatio-temporal oversampling techniques [18], [19]. A new method of determining RN, CVF and other imaging measurements of DSERN image sensors is described.

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54 2. Solid-state Single Photon Counting Imaging Background

55 Since the late 1980's, single photon counting (SPC) and time-gated imaging have been 56 dominated by photo-cathode based intensifier techniques achieving high signal amplification 57 through the 'photo-intensification' of the generated electron cascade through the photo-electric effect 58 using existing charge-coupled device (CCD) and CMOS image sensors (CIS) [1]. However, there are 59 a number of drawbacks which limit their usage dependent on the application. Namely, the 60 wavelength (colour) and spin properties of the photons are lost. Systems have high cost and are 61 physically bulky due to the requirement of operation in a vacuum. Furthermore, photo-cathodes are 62 sensitive to magnetic fields, they have high (kV) operating voltage and also cannot be used in-vivo. 63 Solid-state photon counting image sensor technologies, developed over the last 16 years, address 64 some of these issues.

65 The electron-multiplying CCD (EMCCD) was first demonstrated in 2001 [20], and has recently 66 achieved 0.45e- RN[21]. However, dark current is amplified through the electron multiplication 67 process, and therefore external cooling is employed [22]. The first solid-state CIS pixel array with 68 DSERN appeared in 2015, achieving best-case 0.22e- RN in a remarkable 1.4µm pixel pitch (PP) with 69 403 µV/e- CVF [10]. Later, the first photon-counting CMOS imager achieved 0.27e- RN, by external 70 cooling and a high CVF of 220 µV/e- was realised by removing the reset transistor [23]. Oversampling 71 ADCs have been employed in CIS to reduce all sources of readout noise (1/f, systematic temporal, 72 source follower thermal, etc.) by correlated multiple sampling (CMS). The lowest published CIS RN 73 in voltage (estimated by the author as CVF multiplied by RN) through four sample CMS is 31.7µV 74 RMS [24]. Therefore, with CVF surpassing 400μ V/e- and RN as low as 31.7μ V RMS, CIS with sub 75 0.15e- RN appears not an unreasonable assumption in the near future.

76 Single photon avalanche diode (SPAD) image sensors emerged in 2002 with bump-bonded 77 SPADs [25] onto a digital counter or time-to-digital converter (TDC) per SPAD device recording the 78 time of arrival of single photons. High temporal resolution (≈50ps [26]) permits time resolved 79 imaging such as capturing light-in-flight [27], and seeing round corners [28]. These time correlated 80 single photon counting (TCSPC) sensors have favoured the temporal precision of the photon's arrival 81 over spatial resolution (>44µm) and fill-factor (<4%) which has, so far, restricted the wider adoption 82 of these sensors. The digital circuit providing photon counting or timing occupies the majority of the 83 pixel area to the detriment of photon detection. Chip stacking technology and the use of advanced 84 digital CMOS process technologies are two methods that pitch reduction and fill factor increase will 85 be achieved for SPAD-based image sensors in the future. Regardless of the technology, to realise high 86 fill factor SPAD pixels, a trade-off is made between optical efficiency versus in-pixel functionality or 87 the number of in-pixel transistors; low-transistor count analogue circuits will always be more 88 compact than digital circuits. Our recent research has focused on time resolved photon counting 89 applications using alternative analogue pixel designs that achieve higher fill factor and smaller pixel 90 pitch, namely analogue counters [15], time-to-amplitude converters (TAC) [29], [30] and single bit 91 binary memories [17].

92 Binary SPAD-based imagers, with the capability of recording one SPAD avalanche within an 93 integration time, were first published in 2011 [31] and have recently been published at 65k binary 94 pixels [32] and in our work at 77k binary pixels [17]. Binary black and white imaging is not inherently 95 practical for many imaging applications, therefore spatio-temporal oversampling is employed to 96 create gray levels [14], [19]. SPAD-based image sensors based on analogue counting techniques first 97 appeared in [33] and have recently been demonstrated with 8 to 15µm PP commensurate with CCD, 98 EMCCD and sCMOS image sensors, and fill factor (FF) as high as 26.8% [15], [16], [34]. These sensors 99 achieve time-gating comparable to gated photo-cathodes in the nanosecond [18] and sub nanosecond 100 range [34]. Analogue-based SPAD imagers employ conventional CIS readout techniques and so, to 101 aid comparison with CCD and CIS, equivalent metrics may be applied such as:

- Sensitivity, of the counter circuit to one SPAD avalanche event in mV/SPAD event,
 equivalent to CVF (or CG).
 - Maximum number of SPAD events equivalent to full well.
 - Input referred RN normalising voltage RMS RN to one SPAD event instead of one photoelectron.
- 108 These equivalencies are used throughout this paper. SPAD-based image sensors are the first 109 solid-state imaging technology to have demonstrated sub 0.15e- RN, and as such provide a look-110 ahead to the signal and noise characteristics of DSERN image sensors in CMOS and other 111 technologies.
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113 3. Single Photon Counting Noise Modelling and Analysis

114 The first part of this section details a model of read noise and sensitivity (or CVF) developed to 115 characterise our recent work in SPAD-based imaging. The second part discusses three noise 116 measurement methods for DSERN image sensors based on the photon counting histogram (PCH). 117 The use of single photon counting histograms are not new to the imaging community but the analysis 118 presented here seeks to model and quantify the noise measurements that may be obtained from the 119 PCH. A discrete Poisson probability density function (PDF) may represent photoelectrons (or 120 photons) either from multiple reads of a single pixel or a single read of multiple pixels. For a single 121 pixel '*i*', the PDF for the captured photoelectrons k may be represented as:

$$P(i,k) = \frac{\lambda^k \exp(-\lambda)}{k!} \quad : \quad k \in \mathbb{Z}$$
⁽¹⁾

124 Where λ = mean number of photoelectrons in the integration period. PRNU may be modelled 125 to first order as a normal distribution with mean CVF μ_{CVF} and variance σ_{CVF^2} . For each electron k, the 126 ideal voltage domain input signal S_{IN} is created with the signal from each electrons at a separation 127 $v_{(i,k)}$ equal to the CVF for that pixel 'i':

$$v(i,k) = k \cdot CVF(i)$$
129 (2)

$$S_{IN}(v_{k,i}) = P(i,k)$$
 131 (3)

$$S_{k}(v) = \frac{1}{\sigma_{RN}\sqrt{2\pi}} \cdot exp\left(-\frac{(v - S_{IN}(v_{k}))^{2}}{2\sigma_{RN}^{2}}\right)$$
(4)

161



162

163 Figure 1. Photon counting histogram (PCH) generated by the read noise model with CVF equivalent of 10mV/e, **164** mean λ = 5e- exposure and 0.1e- equivalent RN.

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166 The voltage domain output signal is then represented as the summation of each of the 167 constituent signals for each electron within the PDF:

$$S_{OUT}(v) = \sum_{k=0}^{n} S_k(v)$$

168

Figure 1 provides a photon counting histogram (PCH) example of the output of the model given by Eqn. 5 with 10mV/SPAD event (or 10mV/e- equivalent) and 0.1e- equivalent RN. As seen in the figure, discrete peaks are visible in the PCH. The RN distribution around each photon counting peak can be determined using three recent methods:

173

174 3.1. Valley to Peak Ratio Method

Fossum et al. proposed the Valley to Peak ratio Method (VPM) detailed in [10], [35]. This measures the peak height and the neighbouring valley height (or dip between photon peaks) in the PCH. The VPM has an upper and lower RN measurement limit. Although theoretically possible, it is difficult in practice to obtain peaks and valleys in PCHs in the region of 0.5e- to ≈0.45e- RN giving an upper limit to VPM. At the lower limit, below 0.15e- RN, the VPM is inherently restricted as the valley has reached the 'floor' of the PCH (zero counts in more than one adjacent bin), and a companion method is needed.

(5)

227 3.2. Peak Separation and Width Method

The Peak Separation and Width (PSW) method is proposed in this paper, and has been used in this paper to measure the SPAD-based image sensors in our recent work [15], [16]. The previous VPM measurement evaluates vertically in the PCH, whereas this PSW method operates in the voltage domain or horizontally in the PCH. By determining, the centroid of each single photon counting peak (whether by taking the peak position, or using a centroid weight algorithm, or similar), the peak separation data may provide a number of measurements:

- The sensitivity or CVF per pixel ('i') is established by mean peak separation in a per-pixel
 PCH.
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240

• The PRNU and the average CVF of the sensor are evaluated through a histogram of the compiled peak separation data from step 1 above, taking RMS and mean respectively.

• Vertical, horizontal and pixel to pixel FPN (VPFN, HFPN, PPFPN) are exhibited as horizontal offsets to the peaks, in the set of per pixel PCHs.

The width of each peak is measured to deduce the noise characteristics of the sensor. The full width half maximum (FWHM) of each peak is captured (preferably using interpolative fitting between PCH bins to lessen errors from quantisation and non-linearity in calculations). Assuming the noise around each peak is normally distributed, the FWHM may be converted to standard deviation using the conventional expression:

$$\sigma = \frac{FWHM}{2\sqrt{2\ln 2}} \to \sigma \approx \frac{FWHM}{2.3548}$$
(6)

The interested reader may create a more complete noise model by expanding equations (4) and (6) to take into account other read noise sources (reset, flicker, etc.). Ideally the peak width remains constant across the full signal range, and RN is determined by the mean of the peak width data. However, if a signal dependent noise source is present then the peak widths will increase (and peak heights decrease) for increasing signal. There is no lower limit to the PSW method. However, the upper limit is set by the height of the valley between two peaks: by definition this valley must be lower than half of the two adjacent peak heights which evaluates at < 0.3e- RN approximately.

254

255 3.3. Regressive Modelling and Fitting Method

The third method fits and scales the noise model described above, against a PCH (whether a single exposures of a full sensor or multiple exposures per pixel). This method has been used in [23] to graphically confirm the correct evaluation of RN and mean exposure. This method is expanded here to encompass the previous two methods. First the VPM and PSW are used (as appropriate given their respective limits) to obtain an estimate of RN and CVF to restrict the scaling and fitting 'search' domain. Next the iterative process begins, recording the goodness of fit of the recorded PCH to the modelled PCH and continuing the regression analysis (by whichever chosen fitting method).

263 Like the PSW method, this regression analysis should be performed per pixel to obtain the CVF, 264 PRNU and FPN distributions of the image sensor. Furthermore, as in PSW, ADC non-linearity will 265 affect the regression analysis so some method of interpolation between PCH bins may be necessary. 266 The downside to this method, is its computationally intensive nature and the requirement to have a 267 consistent mean number of photons for exact fitting. The Poisson distribution in Eqn. (1) assumes a 268 constant mean number of photoelectrons (i.e. constant light level) through successive reads of a single 269 pixel, and a constant light level across the array with equal sensitivity (0% PRNU). The advantage of 270 the method is that the model can be expanded to account for known converter non-linearity or other 271 noise sources, such as described in the following sections.

293 4. Analogue Counter and Photon Counting Performance

Single photon counting is achieved in the analogue domain with a SPAD avalanche pulse triggering an integrator circuit based on the principle of the charge transfer amplifier (CTA) whose operation is briefly described here, and in further detail in [15], [16].

297 In reference to Figure 2, the CTA is reset by pulling the main capacitor 'C' to the high reset 298 voltage VRT. The CTA operates by the input gate voltage (in this case the SPAD anode voltage) 299 increasing above the threshold voltage of the input source follower. Charge flows from the main 300 capacitor 'C' to the parasitic capacitor ' $C_{P'}$ and the voltage rises on the parasitic node. The rising 301 voltage pushes the source follower into the cut-off region and the charge flow halts, causing a discrete 302 charge packet to be transferred from the main capacitor for each input pulse. The voltage step 303 sensitivity (CVF equivalent) of CTA pixels is determined by the fixed capacitor ratio (parasitic 304 capacitance 'Cr' divided by integration capacitor 'C') scaling down the input voltage spike. The CTA 305 voltage step (' ΔV_{CTA} ') is bias controllable by 'V_{SOURCE}' and given to a first order by the equation:

$$\Delta V_{CTA} = \left(\frac{C_P}{C}\right) \cdot \left(V_{EB} - V_{SOURCE} - V_{TH}\right)$$
(7)

Where VEB is the excess bias of the SPAD above the breakdown voltage VBD, VSOURCE is the global
 CTA source bias voltage, and VTH is the threshold voltage of the CTA input transistor.

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310



Figure 2. Charge transfer amplifier (CTA) analogue integrator pixel with active pixel sensor (APS)
 readout for global shutter or time-gated SPAD-based photon counting imaging.





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Figure 3. (a) Measured PCH of the analogue counting pixel test structure in [15], (b) Modelled PCH with mean λ = 3 SPAD events, CVF equivalent of 10mV/SPAD event and equivalent 0.02e- RN.







319 320

Figure 4. Measured mean peak separation from a set of PCHs, (a) The relationship of counter sensitivity to SPAD operating voltage, (b) The relationship to CTA VSOURCE voltage.



VSOURCE Bias Linear Full Well Sensitivity from **Input Referred** Equivalent Voltage Voltage (mV) Linear Fit **Read Noise** Linear Full Well (SPAD (mV) (mV / SPAD (SPAD events) Event) **Events**) 200 802.8 14.26 0.064 56 300 722.1 11.23 0.082 64 79 400 651.4 8.21 0.113 500 648.3 5.19 0.178 125

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- 324

 Table 1. Photon counting performance of 320x240 SPAD-based image sensor [16].

325 Figure 3 (a) illustrates an example of the output of one test structure pixel recorded with 1,000 326 repetitions of 30µs integration time and ADC conversion from [15]. 1,000 repetitions was chosen to 327 give an adequate number of data samples versus experimental time. The SPAD is biased at 2.7V VEB 328 above breakdown voltage $V_{BD} \approx 13.4V$. The discrete peaks under a classical Poisson distribution are 329 clearly evident indicating the photon counting in this example is shot noise limited. Fig 3(b) is the 330 side-by-side modelled PCH from a manual regressive modelling and fitting method analysis. The 331 parameters were chosen for the closest found fit, although an offset in the x-axis is still present. In 332 Fig.3 (a), there is a slight 'in-filling' of some data values between the peaks. This is attributed to a 333 distortion mechanism in the passively operated CTA circuit due to the imperfect reset, or incomplete 334 discharge, of the parasitic capacitance CP for short inter-arrival times of two SPAD avalanche events 335 less than 100 ns apart.

The PSW method is performed for the image sensor in [16] to determine the response of the analogue counter to the SPAD excess bias and the source bias voltage. Fig.4 illustrates the relationship of the mean peak separation or image sensor sensitivity to both the SPAD excess bias and the CTA source voltage. The absolute value of the linear gradient fitting parameter indicates the capacitor ratio whilst the offset parameter indicates the other terms in the CTA equation.

341 The linear full well (defined as a deviation of 3% in sensor output from an ideal linear response) is 342 measured against the CTA V_{SOURCE} bias, and the data are presented in Table 1. This demonstrates the 343 trade-off of increasing full well against lower sensitivity and increasing RN.

344

345 4. Analogue Counter Cumulative Noise

346 Through noise measurement and iterative modelling, it is established that the analogue 347 integrator circuits employed in SPAD-based counting pixels suffer from cumulative noise. For each 348 SPAD event, noise affecting the counter circuit modulates the circuit sensitivity, and as the pixel 349 integrates, the noise cumulates. Although the passive CTA pixel suffers from the 'in-filling' distortion 350 mechanism described in the previous section, all analogue integrator structures such as CTAs or 351 switched current sources (SCS) [36] [37] circuits will suffer from cumulative noise to a certain degree. 352 The two main sources of cumulative noise are thermal noise through the switched path (which 353 exhibits as a kT/C noise on the in-pixel capacitor, with the SPAD dead time, or counter switch time, 354 controlling the thermal noise bandwidth) and systematic temporal noise on the common supplies. Of 355 course, for long integration times, 1/f noise in the counter circuit and low frequency temporal noise 356 on the common supplies will also modulate the integrator sensitivity and contribute cumulative 357 noise.

358 The PSW method is employed on one pixel in the test array in [15] to evaluate for this cumulative 359 and signal dependent noise source. Multiple experiments were captured (each with an individual 360 PCH as seen in Figure 3), and for each experiment the integration time (from 1 μ s to 100 μ s) was 361 increased to obtain greater number of SPAD events. An example of the combined PCH is modelled 362 in Figure 5(a). Figure 5(b) extracts the increasing peak width indicating the presence of a cumulative 363 noise source (σ c) from measured data. A linear fit (solid black line) identifies an σ c = 86.9 μ V RMS 364 noise increase per SPAD event. The model shown in Fig.5(a) is matched with 86.9 μ V RMS noise per 365 counter step and the modelled FWHM response is shown alongside (dashed red line) in Fig 5.(b).

The cumulative noise modelled response S_N after N steps can be modelled to first order by expanding equation 4 into an iterative expression assuming the cumulative noise is Gaussian. The initial reset level S_0 (N= 0) is assumed constant with no FPN and no noise terms (a Dirac function). The first modelled counter step S_1 has σ_C cumulative noise applied. The second step S_2 is the convolved response of the first counter step with the same Gaussian cumulative noise, and so on, as an iterative convolution for subsequent counter steps as shown in Equation 8.

$$S_{N}(v_{N}) = \frac{1}{\sigma_{C}\sqrt{2\pi}} \cdot exp\left(-\frac{(v_{N} - S_{N-1}(v_{N-1}))^{2}}{2\sigma_{C}^{2}}\right)$$
(8)

395

Where the v_N represents the voltage range of interest.

The same PSW procedure is performed for the full 320x240 image sensor in [16]. The imager has 700 μ V RMS noise per SPAD event, an increase of approximately 8 times. This is attributed to an increase of kT/C noise due to both the main and parasitic capacitors decreasing in size between the sensors, the capacitance ratio increasing from approximately doubling from 0.013 to 0.03, and an increase in temporal noise due to many more pixels active on the same supplies. Although it is noted, that some fraction of the increase may also be attributed to \approx 1% PRNU which would manifest similarly with a \approx 100 μ V RMS broadening of the peaks per counted photon.

Figure 6(a) gives an example PCH from the imager. Fig. 6 (b) is the PCHs of the noise model applying 700 μ V RMS cumulative noise and 0.06e- RN, and Fig. 6 (c) applying only RN. Fig. 6(b) has a much closer fit to the captured PCH, whereas Fig.6(c) indicates the shape of a PCH that a CIS DSERN sensor with 0.06e- RN should achieve. With such a cumulative noise source, the equivalent input referred read noise increases depending on exposure. Table 2 presents the signal against the equivalent input referred noise figures for both the imager and test structure.

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410

411 Figure 5. (a) Modelled multiple exposure PCH of a signal dependent cumulative noise source in the
412 SPAD-based analogue counter structure [15]. (b) Measured and modelled peak FHWM, the first order
413 linear fit has parameters: offset 204.7μV with cumulative noise FWHM 225.9μV / SPAD event =

⁴¹⁴ $86.9\mu V$ / SPAD event RMS. The modelled data has cumulative noise $86.9\mu V$ / SPAD event applied.

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416

417Figure 6. (a) Measured PCH for all pixels in the 320x240 image sensor in [16]. (b) Modelled PCH (mean418 $\lambda = 1.5e$ -) accounting for both cumulative noise and read noise showing close fit to the measured PCH419(c) Modelled PCH with read noise only showing a different response.

⁴²⁰

No. of SPAD Avalanche Events			
Image Sensor [16]	Test Structure [15]		
2	19		
5	45		
19	160		
	Image Sensor [16] 2 5 19		

Table 2. Equivalent noise at a range of 51 AD events

423

5. Spatio-Temporal Oversampling of Photon Counting Pixels

424 As analogue SPAD pixels suffer from increasing cumulative noise at higher photon counts and 425 the effective full well is restricted, oversampling individual frames at low photon counts provides a 426 means to create an image of high dynamic range with low overall noise. This section addresses trade-427 offs, and details different methods, of spatio-temporal oversampling of photon counting pixels. The 428 Quanta Image Sensor (QIS) framework proposed by Fossum [38], extrapolates the imaging trends of 429 pixel shrink, increasing CVF, decreasing RN, decreasing full well and spatio-temporal oversampling 430 to a concept of a SPC image sensor where a 'pixel' is the spatio-temporal sum of multiple integrations 431 of multiple sub-pixels ('jots').



433

432

Figure 7. Per-pixel spatio-temporal oversampling techniques. (a) Intensity image using IIR with
periodic reset [17]. (b) Time-resolved image: four IIR per pixel [18]. (c) High frame rate intensity image
using first-order FIR per pixel [19].

438 The small full well of photon counting pixels, in the order of magnitude of 100's of 439 photoelectrons or photons, limits a sensor's dynamic range. Spatio-temporal oversampling of 440 multiple pixels may be performed to increase the full well past a single pixel's limit. Furthermore, for 441 DSERN photon counting pixels with cumulative noise such as the SPAD-based analogue pixels 442 described in this paper, the level of the photon counting oversampling threshold (i.e. if pixel output 443 >1 photon or if > 2 photons, etc.) sets the noise of the oversampled output image; a higher 444 oversampling threshold induces greater noise in the output frame image. However, this threshold is 445 traded off against the frame rate and the oversampled full well. A signal level of N photoelectrons 446 can be reached with less oversampled frames (and greater output frame rate) with a higher 447 oversampling threshold of the pixel signal. By setting the threshold above the thermal and 1/f noise 448 floor, the oversampled is truly shot noise limited as little or no thermal and 1/f noise accumulates.

449

450 5.1. Single Photon Binary Quanta Imaging

451 Using SPAD-based single photon image sensors with binary response, a variety of oversampling 452 techniques have been evaluated in our recent work [16][17][18][19] and in the work of others [14], 453 [39]. 'Field' images are individual reads from the image sensor and the oversampled frame is a 454 summation of fields. The simplest technique in order to oversample a set of binary single photon field 455 images, is to temporally or spatially sum a set of input binary pixel (or 'jot') values, to create an output 456 'macro' pixel with grey levels. This is the equivalent operation of a first-order low-pass infinite 457 impulse response (IIR) filter with a periodic filter reset operation as shown in Figure 7 (a). 458 Considering temporal oversampling only (as demonstrated in [17]), to achieve a certain output frame 459 rate in FPS, with oversampled ratio OSR and input binary field rate f, the output rate is: FPS = f/OSR 460 and inversely the IIR reset period = OSR/f, thus attaining an output bit depth of B= Log2(OSR), 461 increasing the image bit depth by a factor of OSR or 2^B. It is clear that to attain frame rates >30FPS, at 462 bit depths B > 5 bit, a high field rate f > 1k fields/s is required from the sensor. In [17], we demonstrated 463 7b bit depth at 40FPS, and 8b at 20FPS with 5.12k global shutter fields per second.

464 SPADs with picosecond temporal precision enable Indirect Time of Flight (ITOF) imaging to be 465 performed. Previous examples are pulsed ITOF using analogue pixels [33] and continuous wave 466 ITOF using digital pixels [40]. However, both approaches had very large pixel pitch and low fill 467 factor. A similar oversampling technique was applied in [18] with compact binary SPAD pixels, to 468 investigate time-gated binary image oversampling to produce a high resolution QVGA Indirect Time 469 of Flight (ITOF) output image as shown in Fig.7(b). Two primary gated field images (A & B) are 470 sequentially captured in interleaved fashion synchronous to a pulsed laser. Two secondary gated 471 images (A' & B') are set with the same time-gate without the laser for background removal. With four 472 field images, the output time-resolved frame rate is therefore a quarter of the previous intensity-only 473 technique (assuming a pipelined division operation).

474 A third technique in [19], addresses the low frame rate, and evaluates a continuous-time moving 475 average operation by applying a first-order low-pass finite impulse response (FIR) filter. As shown 476 in Fig.7(c), the FIR is implemented as a shift-register of length equal to the over-sampling ratio (i.e. a 477 FIR with number of taps = OSR) and a tracking counter. The benefit of this technique is the output 478 frame rate has no relationship with the OSR and is equal to the input field rate of the sensor. The 479 frame rate increase over the IIR technique is at the cost of the shift register per pixel. Longer 480 integration time increases temporal blur, therefore, higher OSR increases image lag of fast moving 481 scene elements. On the other hand, an increased bit depth (from greater OSR) decreases quantisation 482 noise in areas of slow movement in an imaged scene.

483

Reference	[41]	[42]	[16], [17]
Sensor Name	QIS Pathfinder	SwissSPAD	SPC Imager
Process Technology	180nm CMOS	0.35µm HV CMOS	130nm Imaging
			CMOS
Array Size	1376x768	512x128	320 x 240
Photo-detector	'Pump-gate Jot' PD	SPAD	SPAD
NMOS Pixel Transistors	3	11	9
Fill Factor (%)	45	5	26.8
Pixel Pitch (µm)	3.6	24	8
Microlensing	Ν	Y (12x concentration	Ν
		factor)	
Shuttering	Rolling	Global	Global
CDS	True CDS	None	None
Parallel Data Channels	32	128	16
Max. Field Rate (fPS)	1,000	150,000	20,000
Sensor Data Rate	1Gbps	10.24Gbps	1.54Gbps
Pixel CVF or Equivalent	120µV / e-	>1V per SPAD Event	>1V per SPAD
			Event
Bit Error Rate	Not Reported	Not Reported	1.7 x 10-3 BER
Read Noise (e-) or Equivalent	Not Reported	Not Reported	0.168e-
Power During Operation	20mW	1650mW	40.8mW
Power FOMt	2.5pJ/b (ADC only)	168pJ/b	104pJ/b
	19pJ/b (Full Sensor)	(Full Sensor +	(Full Sensor +
		SPADs)	SPADs)

Table 3. Binary capture, oversampled output, quanta image sensor comparison table. †FOM=Sensor
 power/ (No. of Pixel x FPS x N), where N = ADC resolution = 1b for these sensors.

488 We compare our recent work in this area, to two others demonstrating high binary field rates 489 with column parallel single bit flash ADCs for single bit QIS in Table 3. In a 3T CIS implementation 490 [41], amplification and CDS is employed and suitable for pixels with low signal swing (i.e. $CVF \leq$ 491 input-referred offset and read noise). In our work [16] and another SPAD-based example [42], no 492 CDS or column amplifier circuits are required as the pixel sensitivity is >1V/SPAD event which is 493 much greater than offsets and RN. The RN and non-linear exposure characteristics of such 494 oversampled binary imagers are theoretically described in [9] and experimentally confirmed in our 495 work in [16], [18]. The measured bit error rate is 0.0017 providing an equivalent DSERN of 0.168e-. 496 Without CDS timing and increased column current, the field rate more than doubles [16].

497

498 5.2. Multi-photon Binary Quanta Imaging

As previously discussed, setting the oversampling threshold greater than a single counted photon provides a benefit to output frame rate assuming the sensor output data rate remains the same. By setting the oversampling threshold at two photons rather than one, half number of field readouts are required to reach a certain oversampled signal level as each binary bit now represents more than one photon. However, for the SPAD-based analogue counting pixel this is at the cost of oversampling greater cumulative noise, FPN or PRNU with each successive field image.

505 An experiment is performed on the image sensor [16] recording the 'bit density' (the number of 506 pixels outputting a logical high indicating the multi-photon counting threshold is reached) against 507 increasing integration time for a fixed light level. The pixel array in configured in analogue counting 508 CTA mode with V_{SOURCE} = 0.15V. Figure 8 highlights the normalized bit density (D) to normalized 509 exposure (H), where 1.0H=5µs integration time, for an incrementing comparator threshold capturing 510 2 to 8 photons. The theoretical curves from [9] are plotted alongside for comparison. As no CDS is 511 implemented, the high FPN due to column comparator mismatch and source follower threshold 512 variation will effectively induce a PRNU in the measured data for all pixels which is seen as the 513 discrepancy between ideal and measured data particularly in the plotted line for the 4 photon

514 threshold. The closest fit in terms of photon number (2 to 8) is listed in the legend alongside.

515 Figure 9 is the measured normalized RMS noise which has the characteristic shape from Fossum's 516 theoretical Quanta Image Sensor paper in [9]. There are a number of remarkable characteristics of 517 multi-photon threshold binary imaging that are experimentally verified in this noise plot. The rising 518 slope of each of the noise plots indicates the shot-noise dominant region. The 2-photon line 519 demonstrates the "soft-knee" shot noise compression with a smooth roll-off after the peak after H=1.0 520 as expected in 1-photon or 2-photon threshold QIS. The subsequent increasing thresholds show a 521 horizontal shift in the exposure x-axis as a higher number of photons (or equivalent SPAD events) 522 are required to trigger the binary output. This can also be observed in the horizontal shift in the D-523 LogH plot in Fig.8. The maximum noise in the 8-photon threshold is measured as 1.52 times higher 524 than the 2-photon threshold where the theory [9] suggests it should be no more than square root of 525 two higher (1.412 times).

526

527 6. Discussion

528 Table 4 provides a comparison table highlighting a selection of state of the art solid-state photon 529 counting image sensors in the three different technologies (CIS, EMCCD and SPAD). This section 530 discusses and compares the performance of SPAD-based image sensors based on analogue 531 integration. SPAD based image sensors have the highest CVF of solid-state SPC image sensors. 532 Moreover, the pixel size of the SPAD analogue-based imagers is commensurate with EMCCD and 533 sCMOS scientific imagers, although FF is lower. With the exception of the LOFIC pixel which has 534 dual CVF's, like the recent CIS DSERN pixels, the increase in CVF of SPAD pixels yields a reduced 535 full well in the order of 100's photo-electrons or integrated SPAD events.

536 SPADs have the advantage of picosecond temporal resolution. Analogue pixels with low 537 transistor counts permit nanosecond and sub-nanosecond time-gated SPC imaging to be realized 538 where digital pixels further permit TCSPC imaging with 10's ps time resolution at the cost of low 539 spatial resolution.

540 In terms of RN, SPAD analogue integrators share a similar noise characteristic with 3 transistor 541 (3T) CIS pixels in that the integration node is not fully depleted and so suffers from kT/C noise. Our 542 test structure [15] cancels the kT/C noise by implementing 3T-pixel true CDS timing and furthermore 543 implemented 4,096 sample CMS to yield <0.01e- equivalent RN in the best case. However, both 3T 544 timing and >1k sample CMS is very restrictive in an image sensor design preventing, for example, 545 the global shutter or global time-gated operation that our recent work and [37] implements. Therefore 546 delta-reset sampling CDS [43] is implemented in our SPAD analogue counter image sensor which 547 adds a noise component of 100's µV RMS kT/C to the RN. However, the equivalent CVF of the SPAD-548 based analogue pixels in the 10mV range is high enough to compensate, as demonstrated by the 549 0.06e- RN figure which is the lowest in the published SPC image sensor literature.

550 In comparison to other works, analogue integrators suffer from cumulative noise limiting the 551 photon number resolution. Spatio-temporal oversampling, at a few photons per pixel level, mitigates 552 the noise integration whilst extending the photon number resolution although high frame rates are 553 required.





556

Figure 8. Multi-photon threshold oversampled binary imaging normalised bit density to exposure. Ideal curves from [9] are presented alongside measured results.







559

Figure 9. Measured RMS noise in multi-photon threshold oversampled binary imaging.

Reference	[12]	[10]	[23]	[21]	[44]	[15]	[16]	[26]
Photodetector	PIN PD + LOFIC	'Pump- gate Jot' PIN PD	PIN PD	EMCCD	SPAD	SPAD	SPAD	SPAD
Pixel Circuit	5T +LOFIC	4T	4T	CCD	Active CTA 8T	Passive CTA 11T	Passive CTA 9T	7b Counter >100T
Array Size	1280x960	1	35x512	1920x108 0	160x120	3x3	320x240	32x32
Pixel Size (µm)	5.6	1.4	11.2 x 5.6	5.5	15	9.8	8	50
Fill Factor (%)	30.4	-	-	50	21	3.12	26.8	1
Pixel CVF or Equivalent	240µV/e-	403µV/e-	220	Gain depende nt from 44µV/e-	16.5mV/ SPAD event	13.1 to 2mV /SPAD Event	17.4mV to 8.4mV /SPAD event	1 DN / SPAD Event
Full Well or Equivalent	200ke-	210e-	1500e-	20ke- to 160e-	41	80 to 360	56 to 125	127
Read Noise (or Equivalent)	0.41e-	0.22e-	0.27e-	0.45e-	0.08e-	<0.01e- to 0.22e-	0.06e- to 0.18e-	0
Excess Noise	-	-	-	Y	-	-	-	-
Cumulative Noise	-	-	-	-	Y*	Y	Y	-
Measured Cumulative Noise	-	-	-	-	Not Measure d	86.9 μV RMS / SPAD Event	700 μV RMS / SPAD Event	-
Time Gating Width or Temporal Resolution	-	-	-	-	0.75 ns	100 ns	30 ns	52ps

561

Table 4. Solid state single photon counting image sensor comparison table. *As based on a CTA analogue 562 integrator structure, the presence of cumulative noise is assumed by the author.

563

564 7. Conclusion

565 Our recent work on SPAD-based photon counting image sensors is analysed for photon 566 counting performance and deep sub electron equivalent noise characteristics. A noise model is 567 developed to include both CIS RN and the cumulative noise specific to analogue integrator circuits. 568 When combined, the three new methods (VPM, PSW and regressive analysis) of determining RN 569 form a new powerful set of tools for the measurement of most SPC and DSERN image sensor 570 characteristics alongside the existing techniques such as photon transfer curve analysis.

571 These single-photon and multi-photon methods of binary image capture have the attractive 572 quality of similar noise and signal characteristics of photographic film. Future development of these 573 binary photon-counting image sensors is an interesting and new avenue of research. The tradeoff 574 between in-pixel cumulative and spatio-temporal oversampling is examined. Analogue SPC pixels 575 have DSERN but exhibit cumulative noise limiting photon number resolution. As a result they are 576 best operated at low photon number in combination with digital oversampling. A very large dynamic 577 range is conceivably possible, combining the multi-photon counting with an oversampled frame 578 store, which would extend the limited dynamic range of the analogue counter. Furthermore, the 579 frame rate penalty of oversampling is addressed by a continuous-time moving average technique.

580 The capability of an image sensor to capture the arrival of a single photon, is the fundamental

- limit to the detection of quantised electromagnetic radiation. Each of the three solid-state SPC imagesensor technologies, CMOS SPAD, EMCCD and DSERN CIS have specific advantages that will
- 583 individually serve a variety of photon counting applications.
- 584

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 structure, N.D., L.P. and R.H. conceived and designed the image sensor. N.D wrote the paper; N.D., L.P., and
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598 Abbreviations

- 599 The following abbreviations are used in this manuscript:
- 600 CG: Conversion Gain
- 601 CIS: CMOS Image Sensor
- 602 CTA: Charge Transfer Amplifier
- 603 CVF: Charge to Voltage Conversion Factor
- 604 DSERN: Deep Sub Electron Read Noise
- 605 EMCCD: Electron Multiplied Charge Coupled Device
- 606 FIR: Finite Impulse Response Filter
- 607 IIR: Infinite Impulse Response Filter
- 608 PCH: Photon Counting Histogram
- 609 PSW: Peak Seperation and Width method
- 610 QIS: Quanta Image Sensor
- 611 RN: Read Noise
- 612 SPAD: Single Photon Avalanche Diode
- 613 SPC: Single Photon Counting
- 614 TCSPC: Time Correlated Single Photon Counting
- 615 VPM: Valley to Peak method
- 616
- 617

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